

## **REMARKS**

This replaces the paper mailed on August 11, 2004, which was filed in response to the Notice of Non-Compliant Amendment mailed March 18, 2004. Claims 1-5 were previously omitted from the listing. Claims 1-5 were originally allowed in USPN 5,818,249. Claims 6-16 were added in the reissue application. Claims 6-12 are amended by this paper and the amendments are discussed in the paper of December 24, 2003. Claims 1-12 remain in the application.

Entrance of this listing of claims, along with the response filed on December 24, 2003, is respectfully requested.

Claim 6 is amended in its preamble to replace the phrase "of manufacturing integrated circuit chips," with the phrase "for testing semiconductor integrated circuits, the method". The second paragraph of claim 6 is amended to replace "theron" with the word "thereon". The third paragraph of claim 6 is amended to include the phrase, ", wherein said probe card includes structure defining a rectangular through hole having first and second long sides, and wherein the probe needles extend through the rectangular through hole".

Claims 7-9 are amended to remove the phrase "of manufacturing" from their respective preambles. Claim 9 is further amended to replace the phrase "said providing" with the phrase "the step of providing a semiconductor wafer". Claims 10 and 11 are amended by deleting the phrase "manufacturing according to" from their respective preambles.

Claim 12 is amended by adding the following phrase to its third paragraph: ", wherein said probe card includes structure defining a rectangular through hole having first and second long sides, and wherein the probe needles extend through the rectangular through hole".

Appl. No. 09/686,200

Attorney Docket No. 81790.0189

Supplemental Amdt. Dated October 4, 2004

Customer No.: 26021

Reply to Notice of Non-Compliant Amendment (C.F.R. § 1.121)

In view of the foregoing, it is respectfully submitted that the application is in condition for allowance. Reexamination and reconsideration of the application, as amended, are requested.

If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is invited to call the undersigned attorney at the Los Angeles, California telephone number (213) 337-6700 to discuss the steps necessary for placing the application in condition for allowance.

If there are any fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-1314.

Respectfully submitted,

HOGAN & HARTSON L.L.P.

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